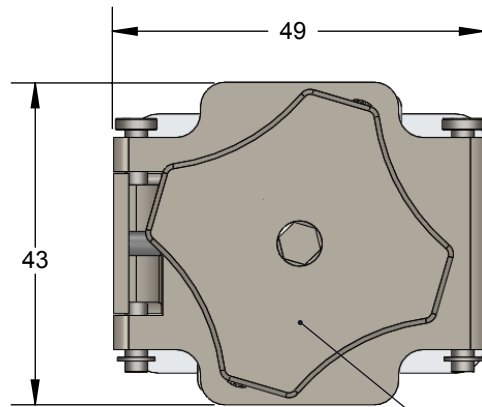
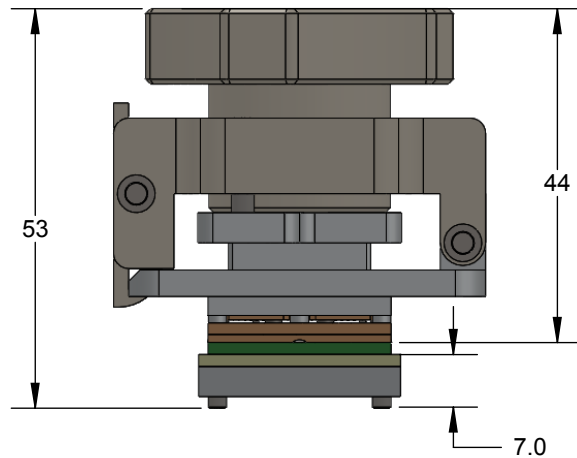


CBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

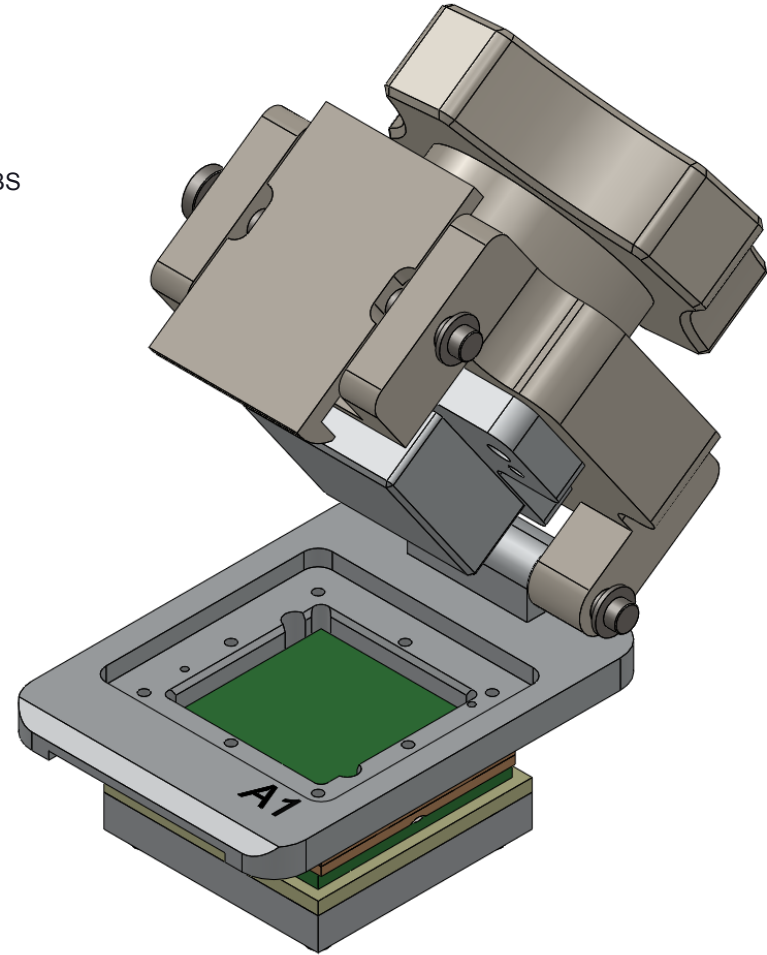


RECOMMENDED TORQUE: 14-21 IN-LBS



FEATURES:


- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time



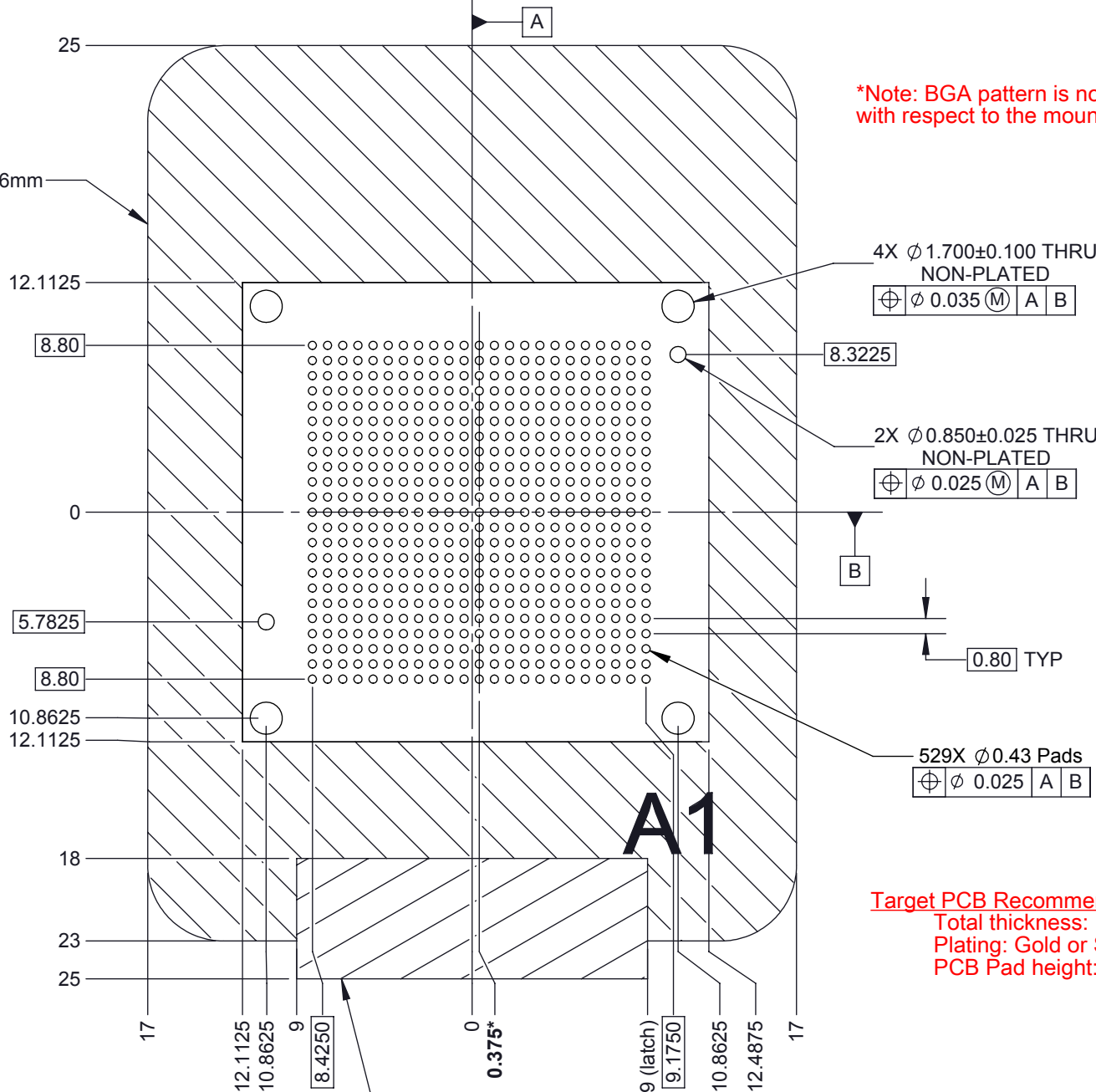
Description: Socket Specification

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 CBT-BGA-6037 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 131.99	STATUS: Released	SHEET: 1 OF 4	REV. B
		ENG: B. Schatz	DRAWN BY: M. Raske	SCALE: 1:1
		FILE: CBT-BGA-6037 Dwg	DATE: 02/14/2014	

SOCKET BASE OUTLINE:
MAX COMPONENT HEIGHT OF 6mm



*Note: BGA pattern is not symmetrical with respect to the mounting holes

4X Ø 1.700±0.100 THRU
NON-PLATED
⊕ Ø 0.035 (M) A B


2X Ø 0.850±0.025 THRU
NON-PLATED
⊕ Ø 0.025 (M) A B

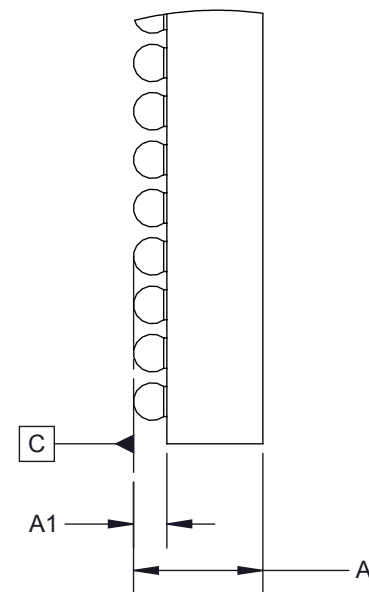
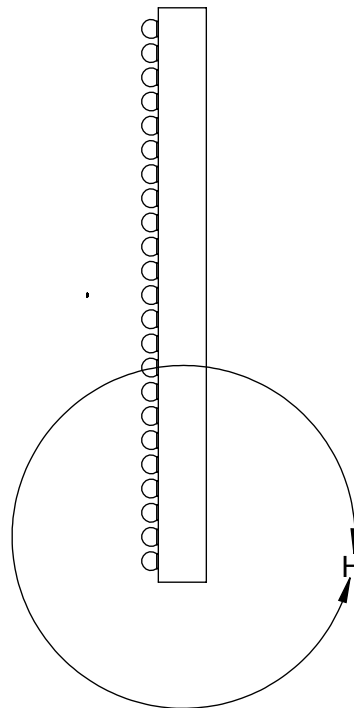
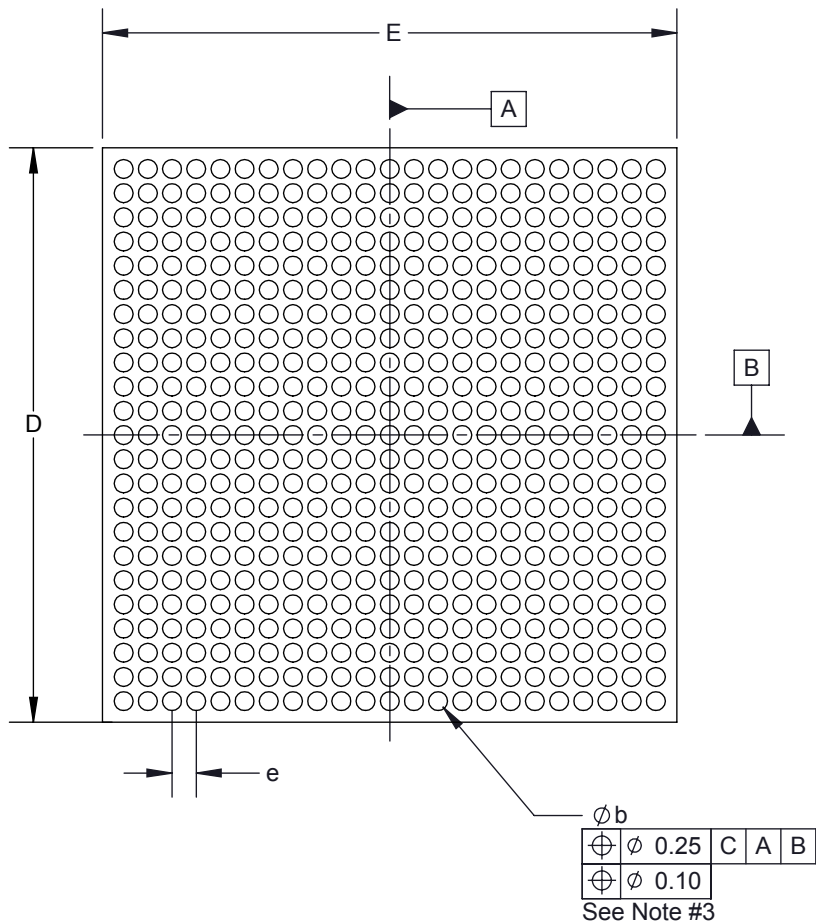
529X Ø 0.43 Pads
⊕ Ø 0.025 A B

Target PCB Recommendations
Total thickness: 1.59mm min.
Plating: Gold or Solder finish
PCB Pad height: max .0508mm
below than solder mask

Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 CBT-BGA-6037 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 131.99	STATUS: Released	SHEET: 2 OF 4	REV. B
		ENG: B. Schatz	DRAWN BY: M. Raske	SCALE: 2:1
		FILE: CBT-BGA-6037 Dwg	DATE: 02/14/2014	



DETAIL H
SCALE 8 : 1

IRONWOOD PACKAGE CODE: BGA529D


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

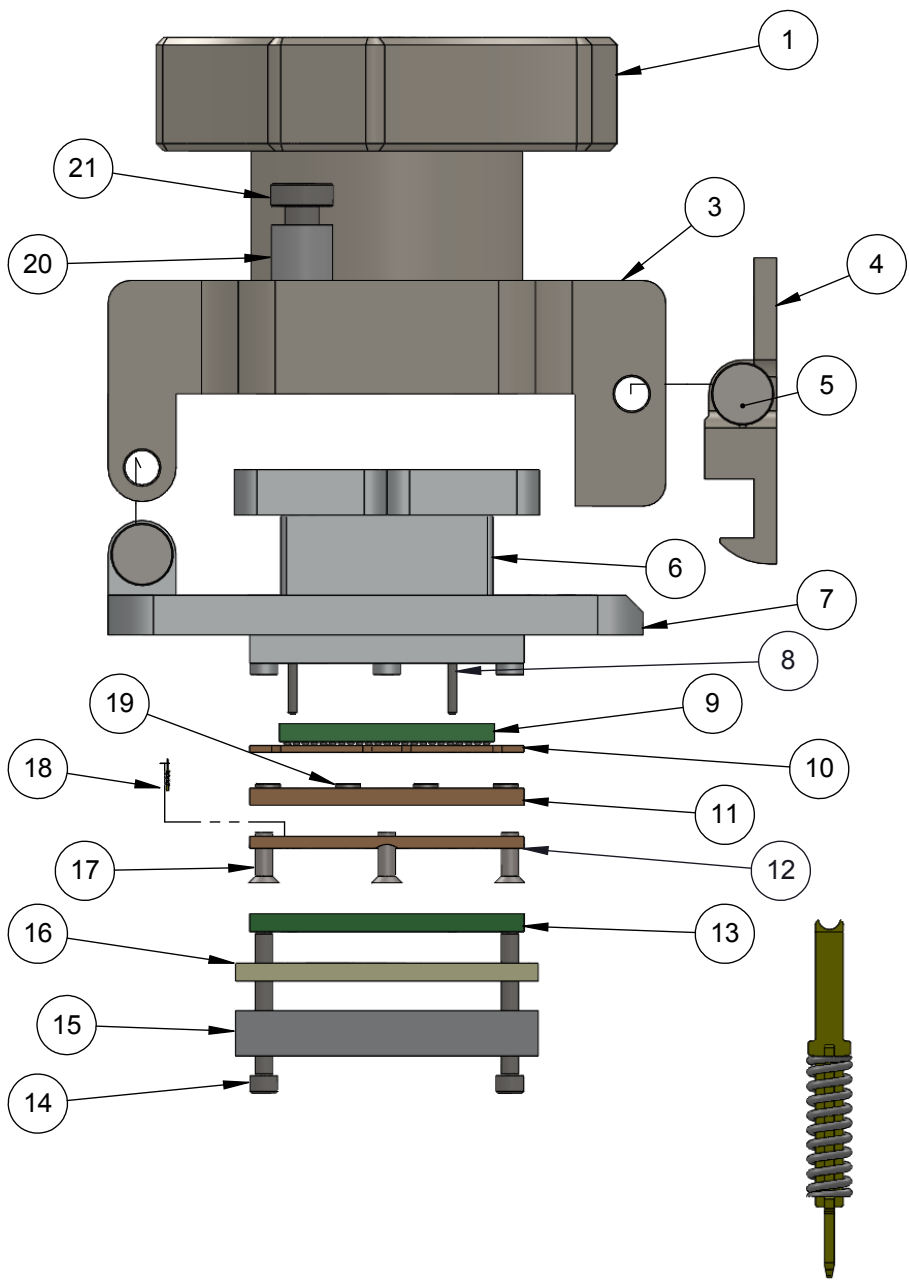
DIM	Minimum	Maximum
A	-	4.0
A1	0.2	0.4
b	-	0.5
D	19.0 +/- 0.2mm	
E	19.0 +/- 0.2mm	
e	0.80	
ARRAY	23 x 23	
PIN COUNT	529	

Description: Compatible BGA

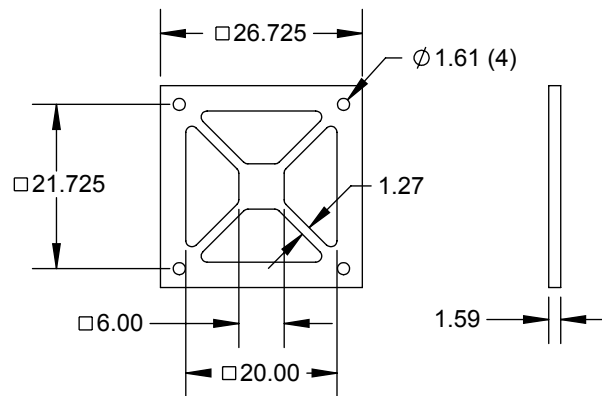
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 CBT-BGA-6037 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 131.99	STATUS: Released ENG: B. Schatz FILE: CBT-BGA-6037 Dwg	SHEET: 3 OF 4 DRAWN BY: M. Raske DATE: 02/14/2014	REV. B SCALE: 1:50



ITEM NO.	Description	Material
1	Compression Screw	7075-T6 Aluminum Alloy
2	Precision Compression Spring	Zinc Plated Music Wire
3	Socket Lid	7075-T6 Aluminum Alloy
4	Latch	7075-T6 Aluminum Alloy
5	Hinge Pin and Snap Ring	AISI 1045 Steel, cold drawn
6	Compression Plate	7075-T6 Aluminum Alloy
7	Socket Base	7075-T6 Aluminum Alloy
8	Dowel pin	Stainless Steel (18-8)
9	BGA529 0.8mm pitch	Material <not specified>
10	Floating Guide	Semitron MDS 100
11	Middle Guide	Semitron MDS 100
12	Bottom Guide	Semitron MDS 100
13	PCB	FR4 Standard
14	0-80 x 0.5" Socket Head Cap Screw	Alloy Steel
15	Backing Plate	7075-T6, Plate (SS)
16	Insulation Plate	FR4 Standard
17	0-80 X .188" Flat Head	PEEK unfilled
18	Spring Pin	
19	Floating Guide Spring	Alloy Steel (SS)
20	Spring Clamshell lid assembly	Steel Music Wire
21	M3 x 12mm Socket Head Cap Screw	18-8 Stainless Steel




SPRING PIN

Insulation Plate Specification

Rev	Date	Initials	Description
A	02/14/14	MR	Original
B	07/08/14	DH	Changed out Pin Guide Screws

Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 CBT-BGA-6037 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 131.99	STATUS: Released ENG: B. Schatz FILE: CBT-BGA-6037 Dwg	SHEET: 4 OF 4 DRAWN BY: M. Raske DATE: 02/14/2014	REV. B SCALE: 3:2
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